



Integrated Device Technology, Inc.
6024 Silver Creek Valley Road, San Jose, CA - 95138

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: TB1201-02	DATE: January 20, 2012	MEANS OF DISTINGUISHING CHANGED DEVICES:
Product Affected: Selective Touch Products (Refer to affected part# in Attachment II)		<input type="checkbox"/> Product Mark <input type="checkbox"/> Back Mark <input type="checkbox"/> Date Code <input checked="" type="checkbox"/> Other
Date Effective: April 20, 2012		Traceability to the test location is maintained by IDT and available on request

Contact: Bimla Paul	Attachment: <input checked="" type="checkbox"/> Yes <input type="checkbox"/> No
Title: Product Quality Assurance	Samples: Availability shown on request
Phone #: (408) 574-6419	
Fax #: (408) 284-8362	
E-mail: Bimla.Paul@idt.com	

DESCRIPTION AND PURPOSE OF CHANGE:

- | | |
|--|---|
| <input type="checkbox"/> Die Technology
<input type="checkbox"/> Wafer Fabrication Process
<input type="checkbox"/> Assembly Process
<input type="checkbox"/> Equipment
<input type="checkbox"/> Material
<input checked="" type="checkbox"/> Testing - Test Site
<input type="checkbox"/> Manufacturing Site
<input type="checkbox"/> Data Sheet
<input checked="" type="checkbox"/> Other - Backend Site | <p>This notification is to advise our customers that IDT is adding IDT Penang, Malaysia as an alternate facility for Test and Backend processes (Coplanarity, Tape & Reel, Bake, Pack and shipment) for the selective Touch products that are presently processed at Chipbond (CTC), Taiwan facility.</p> <p>Attachment I details the change and Attachment II lists the affected part numbers.</p> |
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RELIABILITY/QUALIFICATION SUMMARY:

There is no expected change to the product quality or reliability performance. Please refer to Attachment I for Qual & Electrical correlation data.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.
IDT reserves the right to ship either version manufactured after the process change effective date.

Customer: _____	<input type="checkbox"/> <i>Approval for shipments prior to effective date.</i>
Name/Date: _____	E-Mail Address: _____
Title: _____	Phone# /Fax# : _____

CUSTOMER COMMENTS: _____

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: _____ DATE: _____



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PRODUCT/PROCESS CHANGE NOTICE (PCN)

ATTACHMENT I - PCN # : TB1201-02

PCN Type: Alternate Test and Backend Site

Data Sheet Change: No Change

Details Of Change:

This notification is to advise our customers that IDT is adding IDT Penang, Malaysia as an alternate facility for Test and Backend processes (Coplanarity, Tape & Reel, Bake, Pack and shipment) for the selective Touch products that are presently processed at Chipbond (CTC), Taiwan facility. New products may be processed at this alternate site as it is an IDT qualified Test & Backend site.

This change will allow IDT the flexibility to ship from either facility and will provide the increased capacity, flexibility and shorter lead time to meet market demand.

There is no change in the Test processing flows. Testers, load boards and test programs are compatible at both qualified facilities. IDT has completed the electrical test correlation and based on the test results we do not anticipate any impact on device performance. The testing is fully compatible and transferrable between the test facilities with no change to the test coverage.

There is no change in the Backend processing flows, equipment inspection limits and packaging/packing materials used at the alternate site, IDT Penang.

There is no change in the moisture sensitivity level (MSL).



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ATTACHMENT I - PCN # : TB1201-02

Qualification Information and Qualification Data:

(I) Electrical Test Correlation Results

Vehicle: LDS6120NQGI (NQG40)

Sample size: 1000 electrically good units and 5 reject units

Description	Chipbond, Taiwan (Existing Facility)	IDT Penang, Malaysia (Alternate Facility)
Tester Platform	Advantest ND1	HP83000
Loadboard & Test Program	IDT Load board and Test Program	IDT Load board and Test Program
Test Site	Dual site	Dual site
Test Temperature	25°C	25°C
Test Correlation Results	100%	100%
Number of Good Units Correlated @ 25°C	1000 pcs	1000 pcs
1000 units Bin 1 handler run (good units)	Passed	Passed
Number of Reject Units Correlated @ 25°C	5 pcs	5 pcs
5 units Bin 8 handler run (reject units)	Passed	Passed
10 units Bin 1 datalog correlation (good units)	Passed	Passed
5 units Bin 8 datalog correlation (reject units)	Passed	Passed



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PRODUCT/PROCESS CHANGE NOTICE (PCN)

ATTACHMENT II - PCN # : TB1201-02

Affected Part Number

IDT Part Number	IDT Part Number	IDT Part Number	IDT Part Number
LDS6000NQGI	LDS6020PYGI	LDS6100PVGI	LDS6124NQGI
LDS6000NQGI8	LDS6020PYGI8	LDS6100PVGI8	LDS6124NQGI8
LDS6000PYGI	LDS6023NQGI	LDS6104NQGI	LDS6124PYGI
LDS6000PYGI8	LDS6023NQGI8	LDS6104NQGI8	LDS6124PYGI8
LDS6003NQGI	LDS6023PYGI	LDS6104PYGI	LDS61260APYGI
LDS6003NQGI8	LDS6023PYGI8	LDS6104PYGI8	LDS61260APYGI8
LDS6003PYGI	LDS6025NQGI	LDS6107NQGI	LDS61260BPYGI
LDS6003PYGI8	LDS6025NQGI8	LDS6107NQGI8	LDS61260BPYGI8
LDS6005NQGI	LDS6025PYGI	LDS6107PYGI	LDS6126NQGI
LDS6005NQGI8	LDS6025PYGI8	LDS6107PYGI8	LDS6126NQGI8
LDS6005PYGI	LDS6028NQGI	LDS6108NQGI	LDS6126PYGI
LDS6005PYGI8	LDS6028NQGI8	LDS6108NQGI8	LDS6126PYGI8
LDS6010NQGI	LDS6040NQGI	LDS6108PVGI	LDS6128NQGI
LDS6010NQGI8	LDS6040NQGI8	LDS6108PVGI8	LDS6128NQGI8
LDS6018NQGI	LDS6048NQGI	LDS6120NQGI	LDS6128PVGI
LDS6018NQGI8	LDS6048NQGI8	LDS6120NQGI8	LDS6128PVGI8
LDS6020NQGI	LDS6100NQGI	LDS6120PVGI	
LDS6020NQGI8	LDS6100NQGI8	LDS6120PVGI8	